

LNPTTM THERMOCOMPTM COMPOUND KFB 1 1

KFX-1002 MG

DESCRIPTION

LNP THERMOCOMP KFB 1 1 compound is based on POM (Acetal) copolymer resin containing 5% glass fiber, 5% glass bead. Added features of this grade include: Low Warpage.

GENERAL INFORMATION	
Features	Low Warpage, Dimensional stability, High stiffness/Strength, No PFAS intentionally added
Fillers	Glass Fiber, Glass Bead
Polymer Types	Acetal (POM) Copolymer
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Building and Construction	Building Component
Consumer	Personal Accessory
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, yield	64	MPa	ASTM D638
Tensile Stress, break	62	MPa	ASTM D638
Tensile Strain, yield	4	%	ASTM D638
Tensile Strain, break	5.7	%	ASTM D638
Tensile Modulus, 50 mm/min	4130	MPa	ASTM D638
Flexural Modulus	3440	MPa	ASTM D790
Tensile Stress, yield	65	MPa	ISO 527
Tensile Stress, break	60	MPa	ISO 527
Tensile Strain, yield	3.9	%	ISO 527
Tensile Strain, break	7	%	ISO 527
Tensile Modulus, 1 mm/min	4100	MPa	ISO 527
Flexural Stress	91	MPa	ISO 178
Flexural Modulus	3000	MPa	ISO 178
IMPACT ⁽¹⁾			
Izod Impact, unnotched, 23°C	528	J/m	ASTM D4812
Izod Impact, notched, 23°C	53	J/m	ASTM D256
Instrumented Dart Impact Energy @ peak, 23°C	6	J	ASTM D3763
Multiaxial Impact	1	J	ISO 6603
Izod Impact, unnotched 80*10*4 +23°C	35	kJ/m ²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	5	kJ/m ²	ISO 180/1A

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
THERMAL ⁽¹⁾			
HDT, 0.45 MPa, 3.2 mm, unannealed	162	°C	ASTM D648
HDT, 1.82 MPa, 3.2mm, unannealed	152	°C	ASTM D648
CTE, -40°C to 40°C, flow	8.64E-05	1/°C	ASTM E831
CTE, -40°C to 40°C, xflow	1.08E-04	1/°C	ASTM E831
CTE, -40°C to 40°C, flow	8.60E-05	1/°C	ISO 11359-2
CTE, -40°C to 40°C, xflow	1.07E-04	1/°C	ISO 11359-2
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	161	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	150	°C	ISO 75/Af
PHYSICAL ⁽¹⁾			
Density	1.48	g/cm ³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.2	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	1 – 3	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	1 – 3	%	ASTM D955
Mold Shrinkage, flow, 24 hrs ⁽²⁾	1.9	%	ISO 294
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	1.7	%	ISO 294
Density	1.48	g/cm ³	ISO 1183
INJECTION MOLDING ⁽³⁾			
Drying Temperature	80	°C	
Drying Time	4	Hrs	
Melt Temperature	200 – 215	°C	
Front - Zone 3 Temperature	210 – 220	°C	
Middle - Zone 2 Temperature	195 – 205	°C	
Rear - Zone 1 Temperature	175 – 190	°C	
Mold Temperature	80 – 110	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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